

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
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HENG LEE LEE	11/17/2015
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Property Type	Number
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DATE SIGNED:	11/19/2015
Total Attachments: 1	
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ASSIGNMENT

WHEREAS, I (we), **Heng Lee LEE**
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, is(are) the owner of certain new and useful improvements in

AN INTERGRATED APPARATUS AND METHOD FOR TESTING OF SEMICONDUCTOR COMPONENTS USING A TURRET MACHINE

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

- executed on even date herewith
- executed on:
- filed on: May 24, 2013 U.S. Application No.: 13/901,658 (Now U.S. Patent No. 9,134,342 issued on September 15, 2015)
- established by PCT International Patent Application No.: filed:
designating the United States of America

WHEREAS, **EXIS TECH SDN BHD, Lot 26209, JLN TJ 2/2, Tuanku Jaafar Industrial Park, 71450 Seremban, Negeri Sembilan, Malaysia;** hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States; and

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the INVENTION that are within ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR authorizes any member of the firm of *Bacon & Thomas, PLLC* to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

Assignor Name Heng Lee LEE	Address: c/o EXIS TECH SDN BHD, Lot 26209, JLN TJ 2/2, Tuanku Jaafar Industrial Park, 71450 Seremban, Negeri Sembilan, Malaysia
Where Signed	Signature
Date 17/11/15	(Empty space for date)

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